

Date: - 9 Oct, 2003

Data Sheet Issue:- 2

### **Provisional Data**

# Medium Voltage Thyristor Types K2960T#450 to K2960T#520

Old Type No.: P1263DH45-52

### **Absolute Maximum Ratings**

	VOLTAGE RATINGS	MAXIMUM LIMITS	UNITS
$V_{DRM}$	Repetitive peak off-state voltage, (note 1)	4500-5200	V
$V_{DSM}$	Non-repetitive peak off-state voltage, (note 1)	4500-5200	V
$V_{RRM}$	Repetitive peak reverse voltage, (note 1)	4500-5200	V
$V_{RSM}$	Non-repetitive peak reverse voltage, (note 1)	4600-5300	V

	OTHER RATINGS	MAXIMUM LIMITS	UNITS
I <sub>T(AV)M</sub>	Maximum average on-state current, T <sub>sink</sub> =55°C, (note 2)	2960	Α
$I_{T(AV)M}$	Maximum average on-state current. T <sub>sink</sub> =85°C, (note 2)	2044	Α
$I_{T(AV)M}$	Maximum average on-state current. T <sub>sink</sub> =85°C, (note 3)	1248	Α
I <sub>T(RMS)</sub>	Nominal RMS on-state current, T <sub>sink</sub> =25°C, (note 2)	5825	Α
$I_{T(d.c.)}$	D.C. on-state current, T <sub>sink</sub> =25°C, (note 4)	5095	Α
I <sub>TSM</sub>	Peak non-repetitive surge t <sub>p</sub> =10ms, V <sub>rm</sub> =0.6V <sub>RRM</sub> , (note 5)	32.5	kA
I <sub>TSM2</sub>	Peak non-repetitive surge t <sub>p</sub> =10ms, V <sub>rm</sub> ≤10V, (note 5)	36	kA
l <sup>2</sup> t	I <sup>2</sup> t capacity for fusing t <sub>p</sub> =10ms, V <sub>rm</sub> =0.6V <sub>RRM</sub> , (note 5)	5.28×10 <sup>6</sup>	A <sup>2</sup> s
l <sup>2</sup> t	I <sup>2</sup> t capacity for fusing t <sub>p</sub> =10ms, V <sub>rm</sub> ≤10V, (note 5)	6.48×10 <sup>6</sup>	A <sup>2</sup> s
	Critical rate of rise of on-state current (continuous, 50Hz), (Note 6)	150	A/µs
(di/dt) <sub>cr</sub>	Critical rate of rise of on-state current (repetitive, 50Hz, 60s), (Note 6)	300	A/µs
	Critical rate of rise of on-state current (non-repetitive), (Note 6)	600	A/µs
$V_{RGM}$	Peak reverse gate voltage	5	٧
P <sub>G(AV)</sub>	Mean forward gate power	5	W
P <sub>GM</sub>	Peak forward gate power	50	W
T <sub>j op</sub>	Operating temperature range	-40 to +125	°C
T <sub>stg</sub>	Storage temperature range	-40 to +150	°C

### Notes:-

- 1) De-rating factor of 0.13% per °C is applicable for T<sub>i</sub> below 25°C.
- 2) Double side cooled, single phase; 50Hz, 180° half-sinewave.
- 3) Single side cooled, single phase; 50Hz, 180° half-sinewave.
- 4) Double side cooled.
- 5) Half-sinewave, 125°C T<sub>i</sub> initial.
- 6)  $V_D=67\% \ V_{DRM}, \ I_{FG}=2A, \ t_r \le 0.5 \mu s, \ T_{case}=125 ^{\circ}C.$



## **Characteristics**

	PARAMETER	MIN.	TYP.	MAX.	TEST CONDITIONS (Note 1)	UNITS
V <sub>TM</sub>	Maximum peak on-state voltage	-	-	2.1	I <sub>TM</sub> =4000A	V
$V_{TM}$	Maximum peak on-state voltage	_	_	3.15	I <sub>TM</sub> =8880A	V
$V_{T0}$	Threshold voltage	-	-	1.229		V
r <sub>T</sub>	Slope resistance	_	_	0.212		mΩ
(dv/dt) <sub>cr</sub>	Critical rate of rise of off-state voltage	1000	-	-	V <sub>D</sub> =80% V <sub>DRM</sub> , linear ramp, gate o/c	V/μs
I <sub>DRM</sub>	Peak off-state current	-	_	150	Rated V <sub>DRM</sub>	mA
I <sub>RRM</sub>	Peak reverse current	_	_	150	Rated V <sub>RRM</sub>	mA
$V_{tr}$	On-state recovery voltage	-	18	-	I <sub>T</sub> =2×I <sub>T(AV)M</sub> , t <sub>p</sub> =10ms, T <sub>case</sub> =25°C	V
$V_{GT}$	Gate trigger voltage	-	-	3.0	T 05°C	V
I <sub>GT</sub>	Gate trigger current	-	-	600	$T_j=25^{\circ}C$ $V_D=10V, I_T=3A$	mA
$V_{GD}$	Gate non-trigger voltage	_	_	0.25	Rated V <sub>DRM</sub>	V
I <sub>H</sub>	Holding current	-	-	1000	T <sub>j</sub> =25°C	mA
$t_{gd}$	Gate-controlled turn-on delay time		1.0	2.0	V <sub>D</sub> =60% V <sub>DRM</sub> , I <sub>T</sub> =2000A, di/dt=10A/µs,	μs
t <sub>gt</sub>	Turn-on time	_	3.5	5.0	$I_{FG}$ =2A, $t_r$ =0.5 $\mu$ s, $T_j$ =25 $^{\circ}$ C	μs
Qrr	Recovered charge	-	17000	-		μC
Q <sub>ra</sub>	Recovered charge, 50% Chord	-	11000	12000	  I <sub>TM</sub> =4000A, t <sub>p</sub> =2000μs, di/dt=10A/μs,	μC
I <sub>rm</sub>	Reverse recovery current	-	340	-	V <sub>r</sub> =100V	Α
t <sub>rr</sub>	Reverse recovery time	_	65	-		μs
+	Turn-off time	-	800	-	I <sub>TM</sub> =4000A, t <sub>p</sub> =2000μs, di/dt=10A/μs, V <sub>r</sub> =100V, V <sub>dr</sub> =80%V <sub>DRM</sub> , dV <sub>dr</sub> /dt=20V/μs	II.C
tq	Turn-on ume	-	1600	-	$I_{TM}$ =4000A, $t_p$ =2000 $\mu$ s, di/dt=10A/ $\mu$ s, $V_r$ =100V, $V_{dr}$ =80% $V_{DRM}$ , d $V_{dr}$ /dt=200V/ $\mu$ s	μs
D	Thermal registance, junction to heataink	-	-	0.0085	Double side cooled	K/W
$R_{thJK}$	Thermal resistance, junction to heatsink	-	-	0.017	Single side cooled	K/W
F	Mounting force	63	-	77		kN
		-	1.23	-	Outlines TC & TT	
Wt	Weight	-	1.70	-	Outlines TD & TV	kg

### Notes:-

- 1) Unless otherwise indicated T<sub>i</sub>=125°C.
- 2) For other clamp forces consult factory.

## Notes on rupture rated packages.

This product is available with a non-rupture rated package. For additional details on these products, please consult factory.



### **Notes on Ratings and Characteristics**

### 1.0 Voltage Grade Table

Voltage Grade	$V_{ m DRM}  V_{ m DSM}  V_{ m RRM}                   $	V <sub>RSM</sub> V	V <sub>D</sub> V <sub>R</sub> DC V
45	4500	4600	2100
46	4600	4700	2120
48	4800	4900	2160
50	5000	5100	2200
52	5200	5300	2240

### 2.0 Extension of Voltage Grades

This report is applicable to other voltage grades when supply has been agreed by Sales/Production.

### 3.0 De-rating Factor

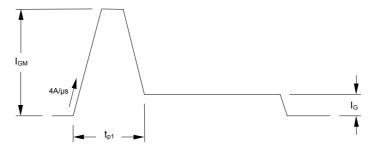
A blocking voltage de-rating factor of 0.13%/°C is applicable to this device for T<sub>i</sub> below 25°C.

### 4.0 Repetitive dv/dt

Standard dv/dt is 1000V/µs.

### 5.0 Gate Drive

The nominal requirement for a typical gate drive is illustrated below. An open circuit voltage of at least 30V is assumed. This gate drive must be applied when using the full di/dt capability of the device.



The magnitude of  $I_{GM}$  should be between five and ten times  $I_{GT}$ , which is shown on page 2. Its duration  $(t_{p1})$  should be 20µs or sufficient to allow the anode current to reach ten times  $I_L$ , whichever is greater. Otherwise, an increase in pulse current could be needed to supply the necessary charge to trigger. The 'back-porch' current  $I_G$  should remain flowing for the same duration as the anode current and have a magnitude in the order of 1.5 times  $I_{GT}$ .

### 6.0 Frequency Ratings

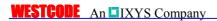
The curves illustrated in figures 17 & 18 are for guidance only and are superseded by the maximum ratings shown on page 1. For operation above line frequency, please consult the factory for assistance.

### 7.0 Rate of rise of on-state current

The maximum un-primed rate of rise of on-state current must not exceed 1000A/µs at any time during turn-on on a non-repetitive basis. For repetitive performance, the on-state rate of rise of current must not exceed 500A/µs at any time during turn-on. Note that these values of rate of rise of current apply to the total device current including that from any local snubber network.

### 8.0 Square wave frequency ratings

These ratings are given for load component rate of rise of on-state current of 50A/µs.



### 9.0 Computer Modelling Parameters

9.1 Device Dissipation Calculations

$$I_{\scriptscriptstyle AV} = \frac{-V_{\scriptscriptstyle T0} + \sqrt{{V_{\scriptscriptstyle T0}}^2 + 4 \cdot \mathit{ff}^2 \cdot \mathit{r}_{\scriptscriptstyle T} \cdot \mathit{W}_{\scriptscriptstyle AV}}}{2 \cdot \mathit{ff}^2 \cdot \mathit{r}_{\scriptscriptstyle T}} \qquad \qquad W_{\scriptscriptstyle AV} = \frac{\Delta T}{R_{\scriptscriptstyle th}} \qquad \qquad \text{and:} \qquad \Delta T = T_{\scriptscriptstyle j \, \text{max}} - T_{\scriptscriptstyle Hs}$$

Where  $V_{T0}\text{=}1.229V,\,r_{T}\text{=}0.212m\Omega,$ 

 $R_{\it th}$  = Supplementary thermal impedance, see table below and

ff = Form factor, see table below.

Supplementary Thermal Impedance							
Conduction Angle	30°	60°	90°	120°	180°	270°	d.c.
Square wave Double Side Cooled	0.00923	0.00915	0.00907	0.00899	0.00884	0.00864	0.0085
Square wave Single Side Cooled	0.01801	0.01792	0.01783	0.01775	0.01760	0.01739	0.0170
Sine wave Double Side Cooled	0.00917	0.00906	0.00898	0.00890	0.00867		
Sine wave Single Side Cooled	0.01794	0.01782	0.01773	0.01765	0.01742		

Form Factors							
Conduction Angle	30°	60°	90°	120°	180°	270°	d.c.
Square wave	3.464	2.449	2	1.732	1.414	1.149	1
Sine wave	3.98	2.778	2.22	1.879	1.57		

### 9.2 D.C. Thermal Impedance Calculation

$$r_{t} = \sum_{p=1}^{p=n} r_{p} \cdot \left(1 - e^{\frac{-t}{\tau_{p}}}\right)$$

Where p = 1 to n, n is the number of terms in the series and:

t = Duration of heating pulse in seconds.

r, = Thermal resistance at time t.

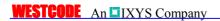
 $r_p$  = Amplitude of  $p_{th}$  term.

 $\tau_p$  = Time Constant of  $r_{th}$  term.

The coefficients for this device are shown in the tables below:

D.C. Double Side Cooled						
Term	Term 1 2 3					
$r_p$	4.934536×10 <sup>-3</sup>	2.693673×10 <sup>-3</sup>	8.295909×10 <sup>-4</sup>			
$ au_{ m p}$	0.8203239	0.1170407	0.0170874			

	D.C. Single Side Cooled						
Term	erm 1 2 3 4						
$r_p$	0.01011545	3.424005×10 <sup>-3</sup>	2.491583×10 <sup>-3</sup>	1.174174×10 <sup>-3</sup>			
$ au_{p}$	5.990464	1.10841	0.140561	0.02103968			



### 9.3 Calculating V<sub>T</sub> using ABCD Coefficients

The on-state characteristic I<sub>T</sub> vs. V<sub>T</sub>, on page 6 is represented in two ways;

- (i) the well established  $V_{T0}$  and  $r_T$  tangent used for rating purposes and
- (ii) a set of constants A, B, C, D, forming the coefficients of the representative equation for  $V_T$  in terms of  $I_T$  given below:

$$V_T = A + B \cdot \ln(I_T) + C \cdot I_T + D \cdot \sqrt{I_T}$$

The constants, derived by curve fitting software, are given below for the hot characteristic. The resulting values for  $V_T$  agree with the true device characteristic over a current range, which is limited to that plotted.

125°C Coefficients						
Α	1.59147985					
В	-0.1394909					
С	1.0635×10 <sup>-4</sup>					
D	0.01960701					

### 10.0 Snubber Components

When selecting snubber components, care must be taken not to use excessively large values of snubber capacitor or excessively small values of snubber resistor. Such excessive component values may lead to device damage due to the large resultant values of snubber discharge current. If required, please consult the factory for assistance.

### 11.0 Reverse recovery ratings

- (i) Q<sub>ra</sub> is based on 50% I<sub>rm</sub> chord as shown in Fig. 1
- (ii)  $Q_{rr}$  is based on a 150 $\mu$ s integration time i.e.

$$Q_{rr} = \int_{0}^{150 \, \mu s} i_{rr}.dt$$

(iii) 
$$K Factor = \frac{t1}{t2}$$

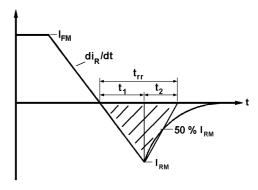


Fig. 1

## 12.0 Duty cycle lines

The 100% duty cycle is represented on the frequency ratings by a straight line. Other duties can be included as parallel to the first.

### **Curves**

Figure 1 - On-state characteristics of Limit device

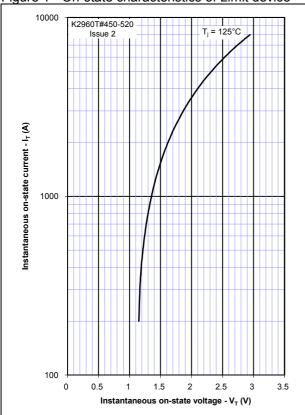


Figure 2 - Transient thermal impedance

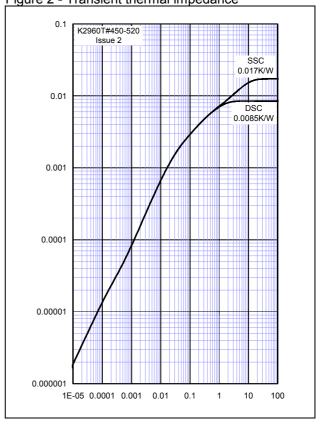


Figure 3 - Gate characteristics - Trigger limits

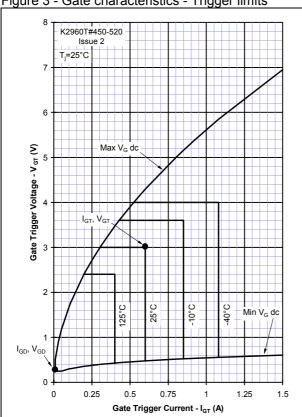


Figure 4 - Gate characteristics - Power curves

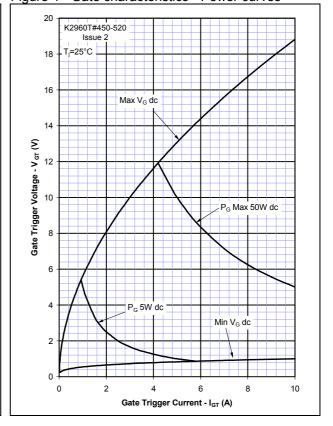


Figure 5 - Total recovered charge, Q<sub>rr</sub>

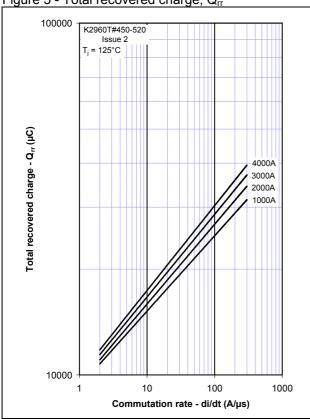
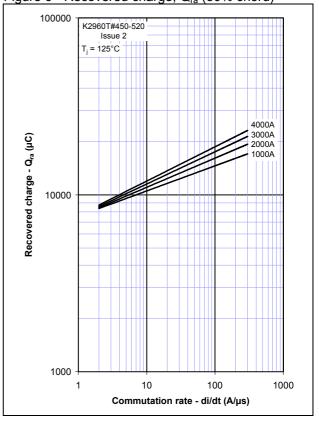


Figure 6 - Recovered charge, Q<sub>ra</sub> (50% chord)



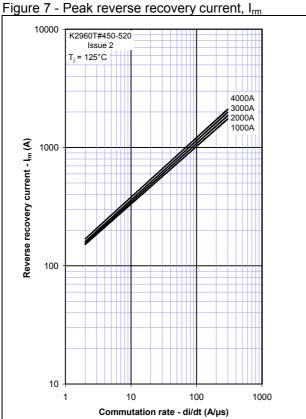


Figure 8 - Maximum recovery time, t<sub>rr</sub> (50% chord)

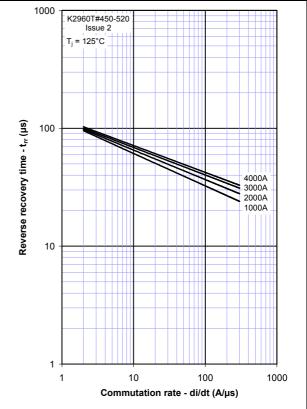


Figure 9 – On-state current vs. Power dissipation – Double Side Cooled (Sine wave)

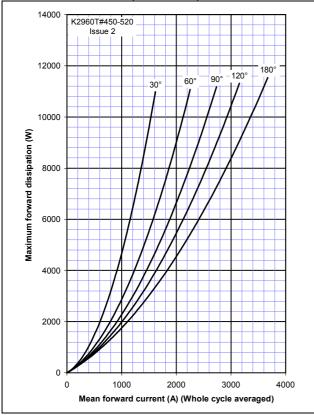


Figure 11 – On-state current vs. Power dissipation – Double Side Cooled (Square wave)

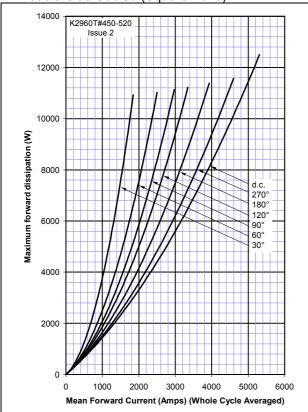


Figure 10 – On-state current vs. Heatsink temperature - Double Side Cooled (Sine wave)

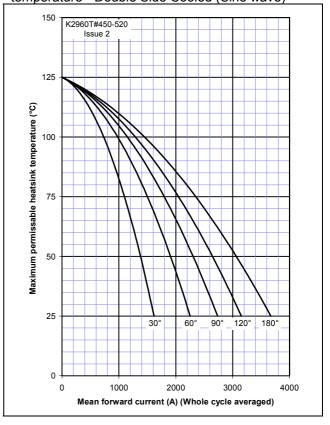


Figure 12 – On-state current vs. Heatsink temperature – Double Side Cooled (Square wave)

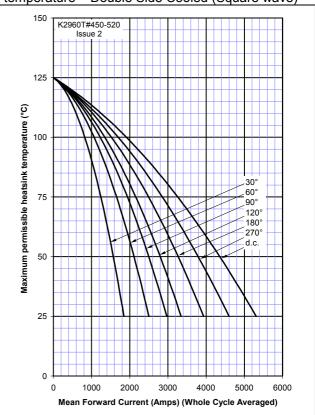


Figure 13 – On-state current vs. Power dissipation – Single Side Cooled (Sine wave)

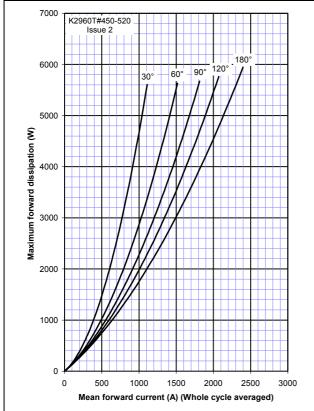


Figure 15 – On-state current vs. Power dissipation – Single Side Cooled (Square wave)

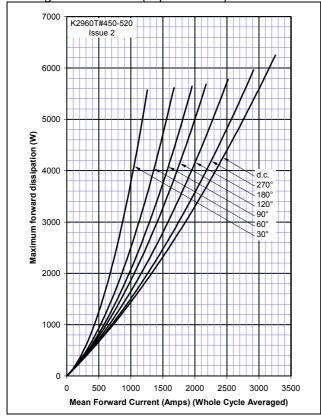


Figure 14 – On-state current vs. Heatsink temperature – Single Side Cooled (Sine wave)

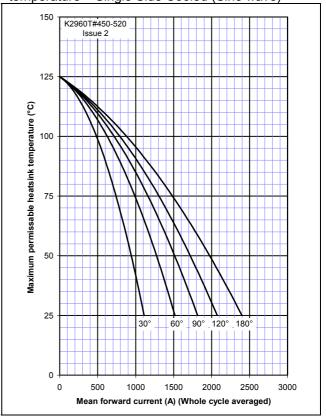
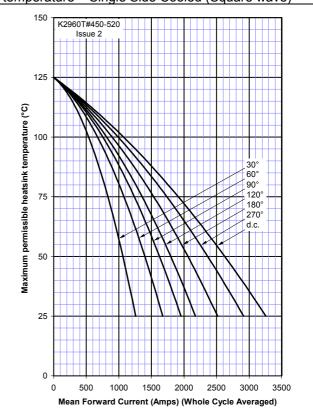
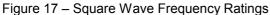


Figure 16 – On-state current vs. Heatsink temperature – Single Side Cooled (Square wave)





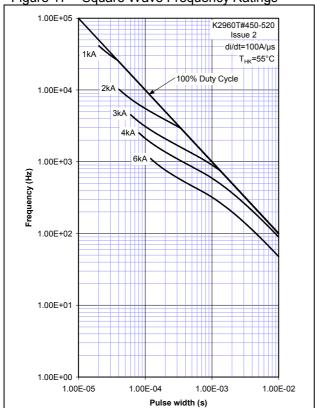


Figure 18 - Sine Wave Frequency Ratings

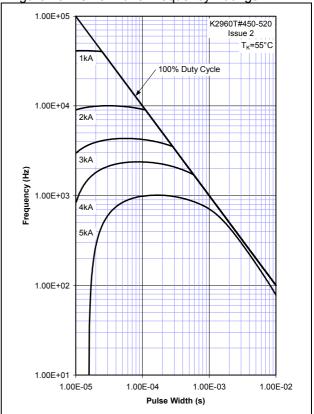
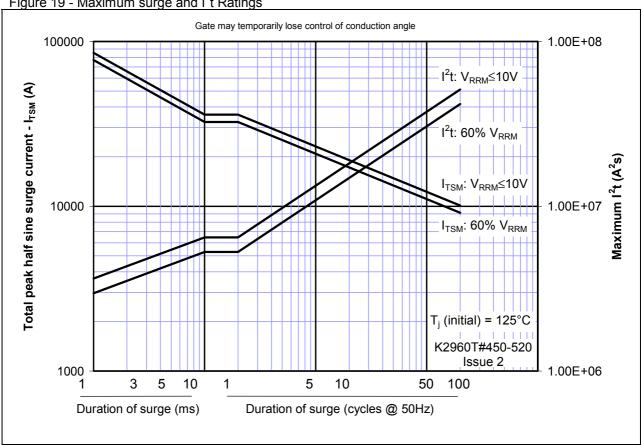
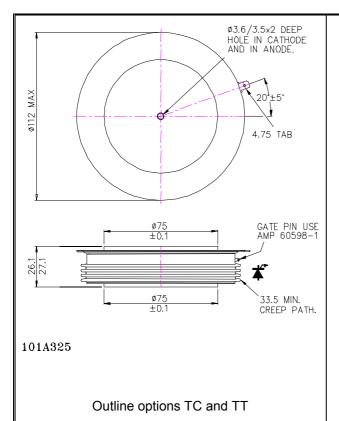


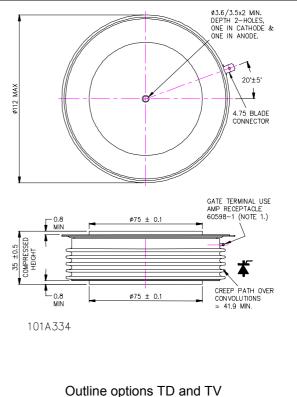
Figure 19 - Maximum surge and I<sup>2</sup>t Ratings





### **Outline Drawing & Ordering Information**





### ORDERING INFORMATION

(Please quote 10 digit code as below)

K2960	<b>**</b>	**	0
Fixed Type Code	Outline Code TC=26.1mm height, TT=26.1mm height, rupture rated TD=33.1mm height, TV=33.1mm height, rupture rated	Voltage code V <sub>DRM</sub> /100 45-52	Fixed turn-off time code

Typical order code: K2960TV500 - 5000V VDRM, VRRM, 33.1mm clamp height, rupture rated capsule.

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